



# Product Change Notification

**Change Notification #:** 118700-01  
**Change Title:** Select 2U Hot-swap 8x3.5 inch Drive Bay Upgrade Kit A2U8X35S3HSDK1, Single, PCN 118700-01, Product Design, HSBP Interposer Implementation  
**Reason for Revision: Updating Change Description**  
**Date of Publication:** December 14, 2021

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material*</b>	December 18, 2021
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

### Reason for Revision: Updating Change Description

Due to Integrated Circuit (IC) shortage from the supplier, a Programmable System-On-Chip (PSOC) used on the Hot Swap Backplanes needs to be replaced with an alternative component.

The new component is identical in function than previous one but differs in form factor. For business continuity, demand fulfillment and to minimize customer impact, an interposer PCB supporting the new component was used. The new component has passed all functional and electrical validation test successfully.

For such reason, products listed in the "Products Affected" table will be delivered to customers with hot swap backplane identified as: G97160-373.

## Customer Impact of Change and Recommended Action:

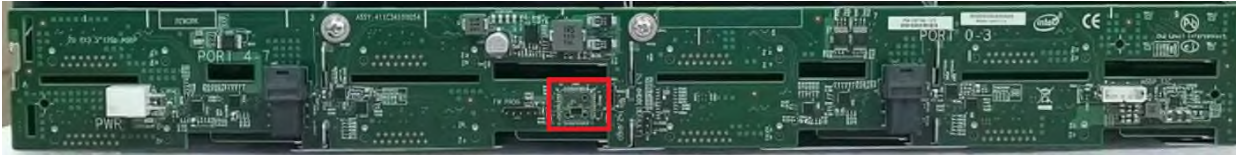
Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Before:



After:



### Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
2U Hot-swap 8x3.5 inch Drive Bay Upgrade Kit A2U8X35S3HSDK1, Single	A2U8X35S3HSDK1	958246	J56722-004	G97160-372	J56722-005	<a href="#">G97160-373</a>

### PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 03, 2021	00	Originally Published PCN
<a href="#">December 14, 2021</a>	<a href="#">01</a>	<a href="#">Updating Change Description</a>



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## 118700-01

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

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